



Applications of Phase Change Materials in Heat Transport Systems

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Message from the Guest Editor

Phase change materials (PCMs) offer an effective passive thermal management solution, absorbing heat at nearly constant temperatures, ensuring minimal temperature fluctuations, and providing high thermal storage density.

Currently, the application of PCM has been widely developed in different heat transport systems, including in the heating and cooling of domestic buildings, solar power plants, solar drying systems, photovoltaic electricity generations, refrigerators, waste heat recovery, and domestic hot water systems.

Keywords:

- phase change materials
- heat transport
- heating
- cooling
- energy system





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